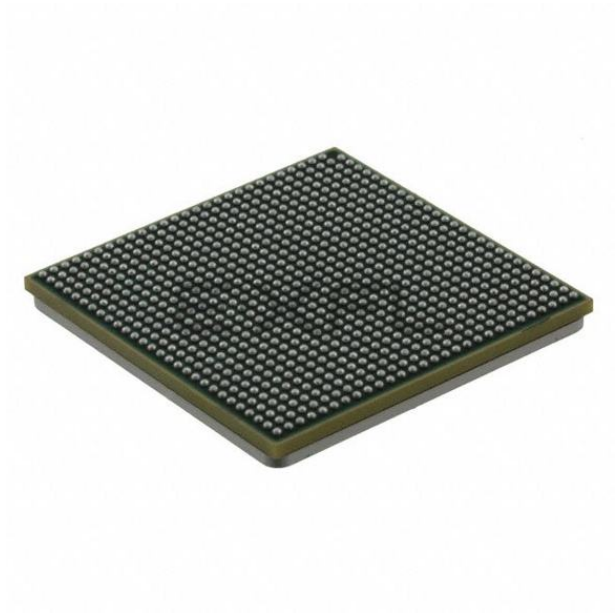

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	PowerPC e500
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	667MHz
Co-Processors/DSP	Signal Processing; SPE, Security; SEC
RAM Controllers	DDR, DDR2, SDRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10/100/1000Mbps (2)
SATA	-
USB	-
Voltage - I/O	1.8V, 2.5V, 3.3V
Operating Temperature	0°C ~ 105°C (TA)
Security Features	Cryptography, Random Number Generator
Package / Case	783-BBGA, FCBGA
Supplier Device Package	783-FCPBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mpc8544edvtalf

Table 25. DC Receiver Electrical Characteristics (continued)

Parameter		Symbol	Min	Typ	Max	Unit	Notes
Input differential voltage	LSTS = 0	V_{rx_diffpp}	100	—	1200	mV	2, 4
	LSTS = 1		175	—			
Loss of signal threshold	LSTS = 0	VI_{os}	30	—	100	mV	3, 4
	LSTS = 1		65	—	175		
Input AC common mode voltage		V_{cm_acpp}	—	—	100	mV	5.
Receiver differential input impedance		Zrx_diff	80	—	120	Ω	—
Receiver common mode input impedance		Zrx_cm	20	—	35	Ω	—
Common mode input voltage		Vcm	xcorevss	—	xcorevss	V	6

Notes:
1. Input must be externally AC-coupled.
2. $V_{RX\_DIFFp\text{-}p}$ is also referred to as peak-to-peak input differential voltage
3. The concept of this parameter is equivalent to the electrical idle detect threshold parameter in PCI Express. Refer to Section 17.4.3, "Differential Receiver (RX) Input Specifications," for further explanation.
4. The LSTS shown in this table refers to the LSTS**CD** bit field of MPC8544E SerDes 2 control register 1.
5. $V_{CM\_ACp\text{-}p}$ is also referred to as peak-to-peak AC common mode voltage.
6. On-chip termination to SGND_SRDS2 (xcorevss).

8.4 SGMII AC Timing Specifications

This section describes the SGMII transmit and receive AC timing specifications. Transmitter and receiver characteristics are measured at the transmitter outputs (SD2_TX[n] and $\overline{\text{SD2\_TX}}$[n]) or at the receiver inputs (SD2_RX[n] and $\overline{\text{SD2\_RX}}$[n]) as depicted in Figure 10, respectively.

8.4.1 SGMII Transmit AC Timing Specifications

Table 26 provides the SGMII transmit AC timing targets. A source synchronous clock is not provided.

Table 26. SGMII Transmit AC Timing Specifications

At recommended operating conditions with XVDD_SRDS2 = 1.0 V ± 5%.

Parameter	Symbol	Min	Typ	Max	Unit	Notes
Deterministic jitter	J_D	—	—	0.17	UI p-p	—
Total jitter	J_T	—	—	0.35	UI p-p	—
Unit interval	U_I	799.92	800	800.08	ps	2
V_{OD} fall time (80%–20%)	t_{fall}	50	—	120	ps	—
V_{OD} rise time (20%–80%)	t_{rise}	50	—	120	ps	—

Notes;
1. Source synchronous clock is not supported.
2. Each UI value is 800 ps ± 100 ppm.

8.7.1 TBI Transmit AC Timing Specifications

Table 34 provides the TBI transmit AC timing specifications.

Table 34. TBI Transmit AC Timing Specifications

At recommended operating conditions with L/TVDD of 3.3 V ± 5% or 2.5 V ± 5%

Parameter/Condition	Symbol[1]	Min	Typ	Max	Unit	Notes
GTX_CLK clock period	t_{GTX}	—	8.0	—	ns	—
GTX_CLK to TCG[9:0] delay time	t_{TTKHDX}	0.2	—	5.0	ns	2
GTX_CLK rise (20%–80%)	t_{TTXR}	—	—	1.0	ns	—
GTX_CLK fall time (80%–20%)	t_{TTXF}	—	—	1.0	ns	—

Notes:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{TTKHDV} symbolizes the TBI transmit timing (TT) with respect to the time from t_{TTX} (K) going high (H) until the referenced data signals (D) reach the valid state (V) or setup time. Also, t_{TTKHDX} symbolizes the TBI transmit timing (TT) with respect to the time from t_{TTX} (K) going high (H) until the referenced data signals (D) reach the invalid state (X) or hold time. Note that, in general, the clock reference symbol representation is based on three letters representing the clock of a particular functional. For example, the subscript of t_{TTX} represents the TBI (T) transmit (TX) clock. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall).
2. Data valid t_{TTKHDV} to GTX_CLK Min setup time is a function of clock period and max hold time (Min setup = cycle time – Max delay).

Figure 19 shows the TBI transmit AC timing diagram.

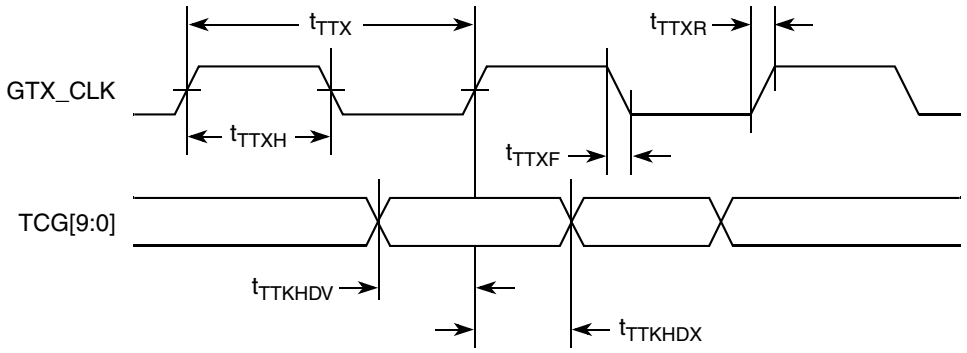


Figure 19. TBI Transmit AC Timing Diagram

8.7.2 TBI Receive AC Timing Specifications

Table 35 provides the TBI receive AC timing specifications.

Table 35. TBI Receive AC Timing Specifications

At recommended operating conditions with L/TVDD of 3.3 V ± 5% or 2.5 V ± 5%.

Parameter/Condition	Symbol[1]	Min	Typ	Max	Unit	Notes
PMA_RX_CLK[0:1] clock period	t_{TRX}	—	16.0	—	ns	—
PMA_RX_CLK[0:1] skew	t_{SKTRX}	7.5	—	8.5	ns	—

A summary of the single-clock TBI mode AC specifications for receive appears in Table 36.

Table 36. TBI Single-Clock Mode Receive AC Timing Specification

Parameter/Condition	Symbol	Min	Typ	Max	Unit	Notes
RX_CLK clock period	t_{TRR}	7.5	8.0	8.5	ns	—
RX_CLK duty cycle	t_{TRRH}	40	50	60	%	—
RX_CLK peak-to-peak jitter	t_{TRRJ}	—	—	250	ps	—
Rise time RX_CLK (20%–80%)	t_{TRRR}	—	—	1.0	ns	—
Fall time RX_CLK (80%–20%)	t_{TRRF}	—	—	1.0	ns	—
RCG[9:0] setup time to RX_CLK rising edge	t_{TRRDV}	2.0	—	—	ns	—
RCG[9:0] hold time to RX_CLK rising edge	t_{TRRDX}	1.0	—	—	ns	—

A timing diagram for TBI receive appears in Figure 21.

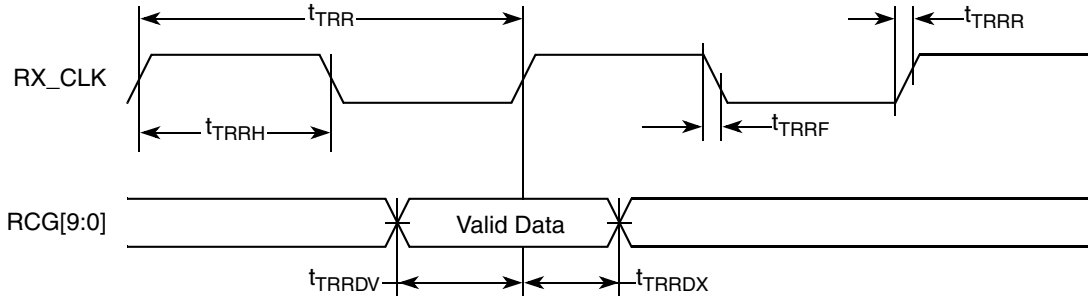


Figure 21. TBI Single-Clock Mode Receive AC Timing Diagram

8.7.4 RGMII and RTBI AC Timing Specifications

Table 37 presents the RGMII and RTBI AC timing specifications.

Table 37. RGMII and RTBI AC Timing Specifications

At recommended operating conditions with L/TV_{DD} of 2.5 V ± 5%.

Parameter/Condition	Symbol[1]	Min	Typ	Max	Unit	Notes
Data to clock output skew (at transmitter)	t_{SKRGT_TX}	–500	0	500	ps	5
Data to clock input skew (at receiver)	t_{SKRGT_RX}	1.0	—	2.8	ns	2
Clock period duration	t_{RGT}	7.2	8.0	8.8	ns	3
Duty cycle for 10BASE-T and 100BASE-TX	t_{RGTH}/t_{RGT}	40	50	60	%	3, 4
Rise time (20%–80%)	t_{RGTR}	—	—	0.75	ns	—

8.7.5 RMII AC Timing Specifications

This section describes the RMII transmit and receive AC timing specifications.

8.7.5.1 RMII Transmit AC Timing Specifications

The RMII transmit AC timing specifications are in Table 38.

Table 38. RMII Transmit AC Timing Specifications

At recommended operating conditions with L/TV_{DD} of 3.3 V ± 5% or 2.5 V ± 5%.

Parameter/Condition	Symbol[1]	Min	Typ	Max	Unit	Notes
REF_CLK clock period	t_{RMT}	15.0	20.0	25.0	ns	—
REF_CLK duty cycle	t_{RMTH}	35	50	65	%	—
REF_CLK peak-to-peak jitter	t_{RMTJ}	—	—	250	ps	—
Rise time REF_CLK (20%–80%)	t_{RMTR}	1.0	—	2.0	ns	—
Fall time REF_CLK (80%–20%)	t_{RMTF}	1.0	—	2.0	ns	—
REF_CLK to RMII data TXD[1:0], TX_EN delay	t_{RMTDX}	1.0	—	10.0	ns	—

Note:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{MTKHDX} symbolizes MII transmit timing (MT) for the time t_{MTX} clock reference (K) going high (H) until data outputs (D) are invalid (X). Note that, in general, the clock reference symbol representation is based on two to three letters representing the clock of a particular functional. For example, the subscript of t_{MTX} represents the MII(M) transmit (TX) clock. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall).

Figure 23 shows the RMII transmit AC timing diagram.

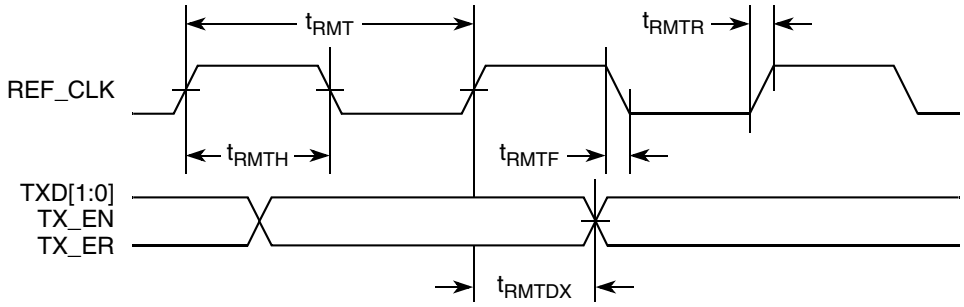


Figure 23. RMII Transmit AC Timing Diagram

8.7.5.2 RMII Receive AC Timing Specifications

Table 39 shows the RMII receive AC timing specifications.

Table 39. RMII Receive AC Timing Specifications

At recommended operating conditions with LV_{DD} of 3.3 V ± 5%.or 2.5 V ± 5%.

Parameter/Condition	Symbol[1]	Min	Typ	Max	Unit	Notes
REF_CLK clock period	t_{RMR}	15.0	20.0	25.0	ns	—
REF_CLK duty cycle	t_{RMRH}	35	50	65	%	—
REF_CLK peak-to-peak jitter	t_{RMRJ}	—	—	250	ps	—
Rise time REF_CLK (20%–80%)	t_{RMRR}	1.0	—	2.0	ns	—
Fall time REF_CLK (80%–20%)	t_{RMRF}	1.0	—	2.0	ns	—
RXD[1:0], CRS_DV, RX_ER setup time to REF_CLK rising edge	t_{RMRDV}	4.0	—	—	ns	—
RXD[1:0], CRS_DV, RX_ER hold time to REF_CLK rising edge	t_{RMRDX}	2.0	—	—	ns	—

Note:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{MRDVKH} symbolizes MII receive timing (MR) with respect to the time data input signals (D) reach the valid state (V) relative to the t_{MRX} clock reference (K) going to the high (H) state or setup time. Also, t_{MRDXKL} symbolizes MII receive timing (GR) with respect to the time data input signals (D) went invalid (X) relative to the t_{MRX} clock reference (K) going to the low (L) state or hold time. Note that, in general, the clock reference symbol representation is based on three letters representing the clock of a particular functional. For example, the subscript of t_{MRX} represents the MII (M) receive (RX) clock. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall).

Figure 24 provides the AC test load for eTSEC.

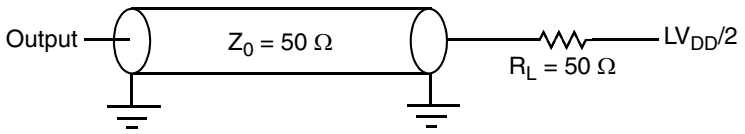


Figure 24. eTSEC AC Test Load

Figure 25 shows the RMII receive AC timing diagram.

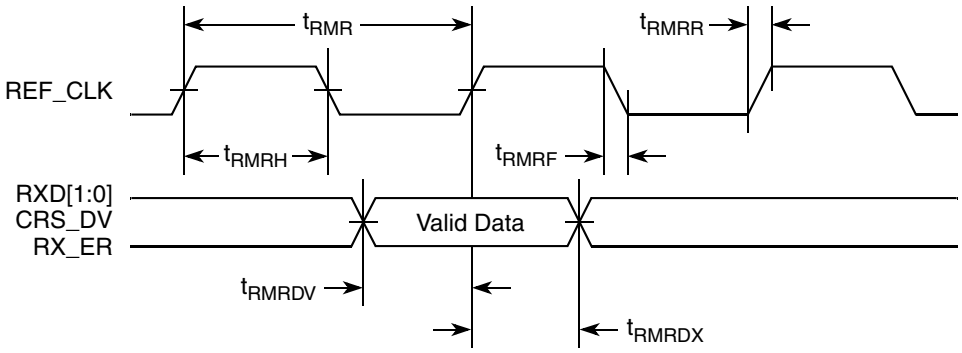


Figure 25. RMII Receive AC Timing Diagram

Table 46. Local Bus General Timing Parameters (BV_{DD} = 2.5 V)—PLL Enabled (continued)

Parameter	Symbol[1]	Min	Max	Unit	Notes
Local bus clock to output high impedance for LAD/LDP	$t_{LBKHOZ2}$	—	2.6	ns	5

Notes:
1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(First two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, $t_{LBIXKH1}$ symbolizes local bus timing (LB) for the input (I) to go invalid (X) with respect to the time the t_{LBK} clock reference (K) goes high (H), in this case for clock one (1). Also, t_{LBKHOX} symbolizes local bus timing (LB) for the t_{LBK} clock reference (K) to go high (H), with respect to the output (O) going invalid (X) or output hold time.
2. All timings are in reference to LSYNC_IN for PLL enabled and internal local bus clock for PLL bypass mode.
3. All signals are measured from $BV_{DD}/2$ of the rising edge of LSYNC_IN for PLL enabled or internal local bus clock for PLL bypass mode to $0.4 \times BV_{DD}$ of the signal in question for 2.5-V signaling levels.
4. Input timings are measured at the pin.
5. For purposes of active/float timing measurements, the Hi-Z or off state is defined to be when the total current delivered through the component pin is less than or equal to the leakage current specification.
6. t_{LBOTOT} is a measurement of the minimum time between the negation of LALE and any change in LAD. t_{LBOTOT} is programmed with the LBCR[AHD] parameter.
7. Maximum possible clock skew between a clock LCLK[m] and a relative clock LCLK[n]. Skew measured between complementary signals at $BV_{DD}/2$.

Table 47 describes the general timing parameters of the local bus interface at BV_{DD} = 1.8 V DC.

Table 47. Local Bus General Timing Parameters (BV_{DD} = 1.8 V DC)

Parameter	Symbol[1]	Min	Max	Unit	Notes
Local bus cycle time	t_{LBK}	7.5	12	ns	2
Local bus duty cycle	t_{LBKH}/t_{LBK}	43	57	%	—
LCLK[n] skew to LCLK[m] or LSYNC_OUT	$t_{LBKSKEW}$	—	150	ps	7
Input setup to local bus clock (except LUPWAIT)	$t_{LBIVKH1}$	2.6	—	ns	3, 4
LUPWAIT input setup to local bus clock	$t_{LBIVKH2}$	1.9	—	ns	3, 4
Input hold from local bus clock (except LUPWAIT)	$t_{LBIXKH1}$	1.1	—	ns	3, 4
LUPWAIT input hold from local bus clock	$t_{LBIXKH2}$	1.1	—	ns	3, 4
LALE output transition to LAD/LDP output transition (LATCH setup and hold time)	t_{LBOTOT}	1.2	—	ns	6
Local bus clock to output valid (except LAD/LDP and LALE)	$t_{LBKHOV1}$	—	3.2	ns	—
Local bus clock to data valid for LAD/LDP	$t_{LBKHOV2}$	—	3.2	ns	3
Local bus clock to address valid for LAD	$t_{LBKHOV3}$	—	3.2	ns	3
Local bus clock to LALE assertion	$t_{LBKHOV4}$	—	3.2	ns	3
Output hold from local bus clock (except LAD/LDP and LALE)	$t_{LBKHOX1}$	0.9	—	ns	3
Output hold from local bus clock for LAD/LDP	$t_{LBKHOX2}$	0.9	—	ns	3
Local bus clock to output high Impedance (except LAD/LDP and LALE)	$t_{LBKHOZ1}$	—	2.6	ns	5

Figure 28 through Figure 33 show the local bus signals.

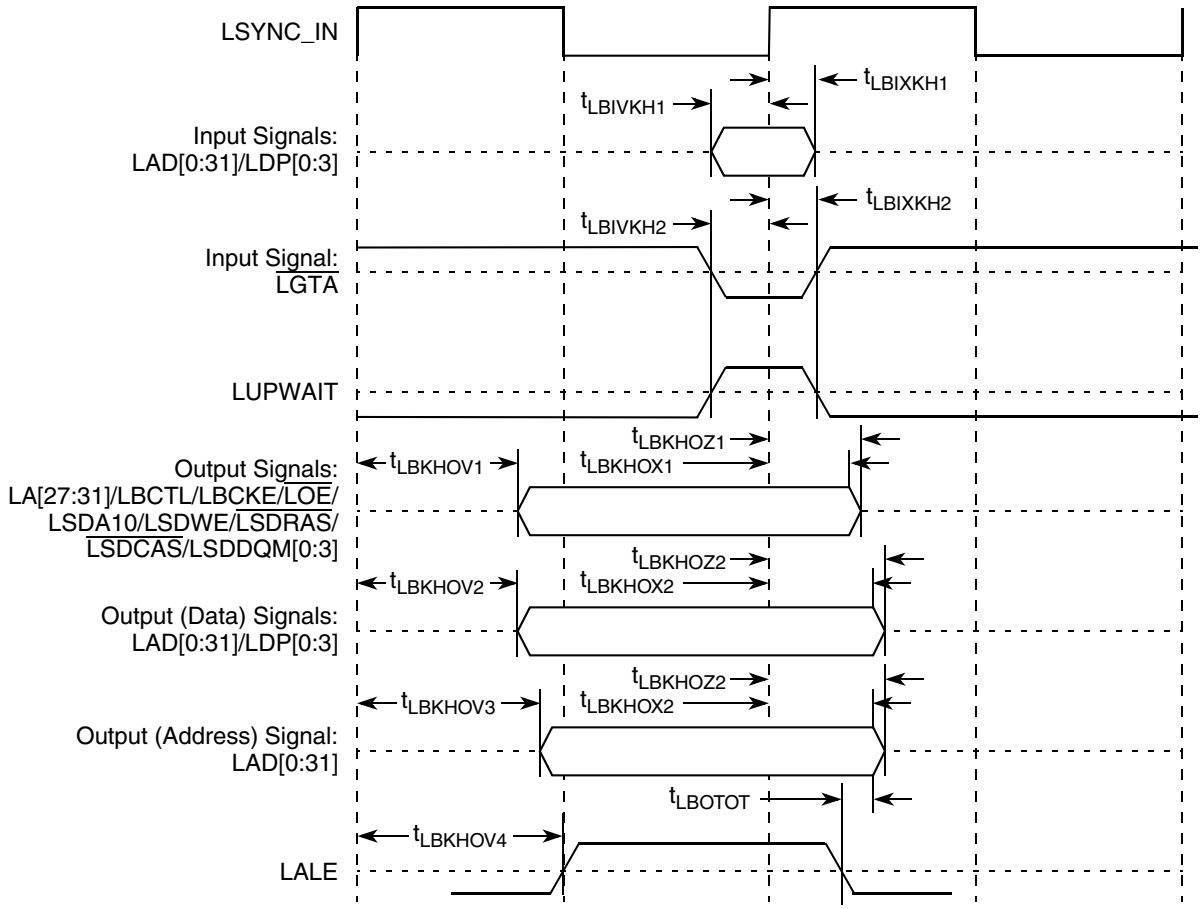


Figure 28. Local Bus Signals (PLL Enabled)

Table 48 describes the general timing parameters of the local bus interface at V_{DD} = 3.3 V DC with PLL disabled.

Table 48. Local Bus General Timing Parameters—PLL Bypassed

Parameter	Symbol[1]	Min	Max	Unit	Notes
Local bus cycle time	t_{LBK}	12	—	ns	2
Local bus duty cycle	t_{LBKH}/t_{LBK}	43	57	%	—
Internal launch/capture clock to LCLK delay	t_{LBKHKT}	1.2	4.9	ns	—
Input setup to local bus clock (except LUPWAIT)	$t_{LBIVKH1}$	7.4	—	ns	4, 5
LUPWAIT input setup to local bus clock	$t_{LBIVKL2}$	6.75	—	ns	4, 5
Input hold from local bus clock (except LUPWAIT)	$t_{LBIXKH1}$	–0.2	—	ns	4, 5
LUPWAIT input hold from local bus clock	$t_{LBIXKL2}$	–0.2	—	ns	4, 5
LALE output transition to LAD/LDP output transition (LATCH hold time)	t_{LBOTOT}	1.5	—	ns	6
Local bus clock to output valid (except LAD/LDP and LALE)	$t_{LBKLOV1}$	—	1.6	ns	—

12 JTAG

This section describes the AC electrical specifications for the IEEE 1149.1 (JTAG) interface of the MPC8544E.

12.1 JTAG DC Electrical Characteristics

Table 49 provides the DC electrical characteristics for the JTAG interface.

Table 49. JTAG DC Electrical Characteristics

Parameter	Symbol	Min	Max	Unit	Notes
High-level input voltage	V_{IH}	2	OV_{DD} + 0.3	V	—
Low-level input voltage	V_{IL}	–0.3	0.8	V	—
Input current (OV_{IN} = 0 V or OV_{IN} = OV_{DD})	I_{IN}	—	±5	μA	1
High-level output voltage (OV_{DD} = min, I_{OH} = –2 mA)	V_{OH}	2.4	—	V	—
Low-level output voltage (OV_{DD} = min, I_{OL} = 2 mA)	V_{OL}	—	0.4	V	—

Note:
1. Note that the symbol V_{IN}, in this case, represents the OV_{IN}.

12.2 JTAG AC Electrical Specifications

Table 50 provides the JTAG AC timing specifications as defined in Figure 34 through Figure 37.

Table 50. JTAG AC Timing Specifications (Independent of SYSCLK)[1]

At recommended operating conditions (see Table 3).

Parameter	Symbol[2]	Min	Max	Unit	Notes
JTAG external clock frequency of operation	f_{JTG}	0	33.3	MHz	—
JTAG external clock cycle time	t_{JTG}	30	—	ns	—
JTAG external clock pulse width measured at 1.4 V	t_{JTKHKL}	15	—	ns	—
JTAG external clock rise and fall times	t_{JTGR} & t_{JTGF}	0	2	ns	—
$\overline{\text{TRST}}$ assert time	t_{TRST}	25	—	ns	3
Input setup times: Boundary-scan data TMS, TDI	 t_{JTDVKH} t_{JTIVKH}	 4 0	 — —	ns	4
Input hold times: Boundary-scan data TMS, TDI	 t_{JTDXKH} t_{JTIXKH}	 20 25	 — —	ns	4
Valid times: Boundary-scan data TDO	 t_{JTKLDV} t_{JTKLOV}	 4 4	 20 25	ns	5
Output hold times: Boundary-scan data TDO	 t_{JTKLDX} t_{JTKLOX}	 2.5 4	 — —	ns	5

13.2 I²C AC Electrical Specifications

Table 52 provides the AC timing parameters for the I²C interfaces.

Table 52. I²C AC Electrical Specifications

All values refer to V_{IH} (min) and V_{IL} (max) levels (see Table 51).

Parameter	Symbol[1]	Min	Max	Unit	Notes
SCL clock frequency	f_{I2C}	0	400	kHz	—
Low period of the SCL clock	t_{I2CL}	1.3	—	μs	—
High period of the SCL clock	t_{I2CH}	0.6	—	μs	—
Setup time for a repeated START condition	t_{I2SVKH}	0.6	—	μs	—
Hold time (repeated) START condition (after this period, the first clock pulse is generated)	t_{I2SXKL}	0.6	—	μs	—
Data setup time	t_{I2DVKH}	100	—	ns	—
Data hold time: CBUS compatible masters I²C bus devices	t_{I2DXKL}	 — 0	 — —	μs	2
Data output delay time	t_{I2OVKL}	—	0.9		3
Set-up time for STOP condition	t_{I2PVKH}	0.6	—	μs	—
Rise time of both SDA and SCL signals	t_{I2CR}	$20 + 0.1\ C_b$	300	ns	4
Fall time of both SDA and SCL signals	t_{I2CF}	$20 + 0.1\ C_b$	300	ns	4
Bus free time between a STOP and START condition	t_{I2KHDX}	1.3	—	μs	—
Noise margin at the LOW level for each connected device (including hysteresis)	V_{NL}	$0.1 \times OV_{DD}$	—	V	—
Noise margin at the HIGH level for each connected device (including hysteresis)	V_{NH}	$0.2 \times OV_{DD}$	—	V	—

Notes:

1. The symbols used for timing specifications follow the pattern of $t_{\text{(first two letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{I2DVKH} symbolizes I²C timing (I2) with respect to the time data input signals (D) reach the valid state (V) relative to the t_{I2C} clock reference (K) going to the high (H) state or setup time. Also, t_{I2SXKL} symbolizes I²C timing (I2) for the time that the data with respect to the start condition (S) went invalid (X) relative to the t_{I2C} clock reference (K) going to the low (L) state or hold time. Also, t_{I2PVKH} symbolizes I²C timing (I2) for the time that the data with respect to the stop condition (P) reaching the valid state (V) relative to the t_{I2C} clock reference (K) going to the high (H) state or setup time. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall).
2. The MPC8544E provides a hold time of at least 300 ns for the SDA signal (referred to the V_{IH}min of the SCL signal) to bridge the undefined region of the falling edge of SCL.
3. The maximum t_{I2DXKL} has only to be met if the device does not stretch the LOW period (t_{I2CL}) of the SCL signal.
4. C_B = capacitance of one bus line in pF.

16.2.4 AC Requirements for SerDes Reference Clocks

The clock driver selected should provide a high quality reference clock with low phase noise and cycle-to-cycle jitter. Phase noise less than 100 kHz can be tracked by the PLL and data recovery loops and is less of a problem. Phase noise above 15 MHz is filtered by the PLL. The most problematic phase noise occurs in the 1–15 MHz range. The source impedance of the clock driver should be 50 Ω to match the transmission line and reduce reflections which are a source of noise to the system.

Table 57 describes some AC parameters common to SGMII, and PCI Express protocols.

Table 57. SerDes Reference Clock Common AC Parameters

Parameter	Symbol	Min	Max	Unit	Notes
Rising Edge Rate	Rise Edge Rate	1.0	4.0	V/ns	2, 3
Falling Edge Rate	Fall Edge Rate	1.0	4.0	V/ns	2, 3
Differential Input High Voltage	V_{IH}	+200	—	mV	2
Differential Input Low Voltage	V_{IL}	—	–200	mV	2
Rising edge rate (SD*n*_REF_CLK) to falling edge rate ($\overline{\text{SD}n\text{\_REF\_CLK}}$) matching	Rise-Fall Matching	—	20	%	1, 4

Notes:
1. Measurement taken from single ended waveform.
2. Measurement taken from differential waveform.
3. Measured from –200 mV to +200 mV on the differential waveform (derived from SD*n*_REF_CLK minus $\overline{\text{SD}n\text{\_REF\_CLK}}$). The signal must be monotonic through the measurement region for rise and fall time. The 400 mV measurement window is centered on the differential zero crossing. See Figure 53.
4. Matching applies to rising edge rate for SD*n*_REF_CLK and falling edge rate for $\overline{\text{SD}n\text{\_REF\_CLK}}$. It is measured using a 200 mV window centered on the median cross point where SD*n*_REF_CLK rising meets $\overline{\text{SD}n\text{\_REF\_CLK}}$ falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations. The rise edge rate of SD*n*_REF_CLK should be compared to the fall edge rate of $\overline{\text{SD}n\text{\_REF\_CLK}}$, the maximum allowed difference should not exceed 20% of the slowest edge rate. See Figure 54.

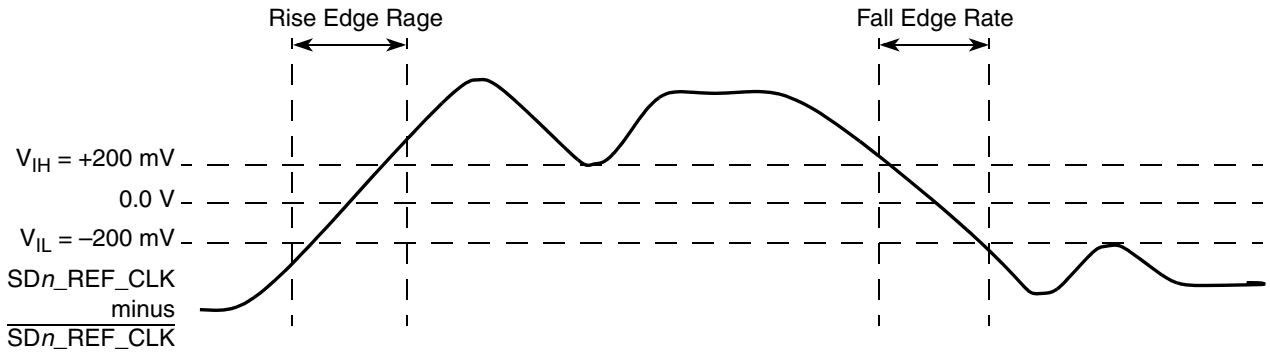


Figure 53. Differential Measurement Points for Rise and Fall Time

Table 59. Differential Transmitter (TX) Output Specifications (continued)

Symbol	Parameter	Min	Nom	Max	Unit	Comments
$V_{TX\text{-}RCV\text{-}DETECT}$	Amount of voltage change allowed during receiver detection	—	—	600	mV	The total amount of voltage change that a transmitter can apply to sense whether a low impedance receiver is present. See Note 6.
$V_{TX\text{-}DC\text{-}CM}$	TX DC common mode voltage	0	—	3.6	V	The allowed DC common mode voltage under any conditions. See Note 6.
$I_{TX\text{-}SHORT}$	TX short circuit current limit	—	—	90	mA	The total current the transmitter can provide when shorted to its ground.
$T_{TX\text{-}IDLE\text{-}MIN}$	Minimum time spent in electrical idle	50	—	—	UI	Minimum time a transmitter must be in electrical idle utilized by the receiver to start looking for an electrical idle exit after successfully receiving an electrical idle ordered set.
$T_{TX\text{-}IDLE\text{-}SET\text{-}TO\text{-}IDLE}$	Maximum time to transition to a valid electrical idle after sending an electrical Idle ordered set	—	—	20	UI	After sending an electrical idle ordered set, the transmitter must meet all electrical idle specifications within this time. This is considered a debounce time for the transmitter to meet electrical idle after transitioning from LO.
$T_{TX\text{-}IDLE\text{-}TO\text{-}DIFF\text{-}DATA}$	Maximum time to transition to valid TX specifications after leaving an electrical idle condition	—	—	20	UI	Maximum time to meet all TX specifications when transitioning from electrical idle to sending differential data. This is considered a debounce time for the TX to meet all TX specifications after leaving electrical idle.
$RL_{TX\text{-}DIFF}$	Differential return loss	12	—	—	dB	Measured over 50 MHz to 1.25 GHz. See Note 4.
$RL_{TX\text{-}CM}$	Common mode return loss	6	—	—	dB	Measured over 50 MHz to 1.25 GHz. See Note 4.
$Z_{TX\text{-}DIFF\text{-}DC}$	DC differential TX impedance	80	100	120	Ω	TX DC differential mode low impedance.
$Z_{TX\text{-}DC}$	Transmitter DC impedance	40	—	—	Ω	Required TX D+ as well as D– DC Impedance during all states.
$L_{TX\text{-}SKEW}$	Lane-to-lane output skew	—	—	500 + 2 UI	ps	Static skew between any two transmitter lanes within a single link.
C_{TX}	AC coupling capacitor	75	—	200	nF	All transmitters shall be AC coupled. The AC coupling is required either within the media or within the transmitting component itself.

The eye diagram must be valid for any 250 consecutive UIs.

A recovered TX UI is calculated over 3500 consecutive unit intervals of sample data. The eye diagram is created using all edges of the 250 consecutive UI in the center of the 3500 UI used for calculating the TX UI.

NOTE

The reference impedance for return loss measurements is 50 Ω to ground for both the D+ and D– line (that is, as measured by a vector network analyzer with 50-Ω probes, see Figure 57). Note that the series capacitors, CTX, are optional for the return loss measurement.

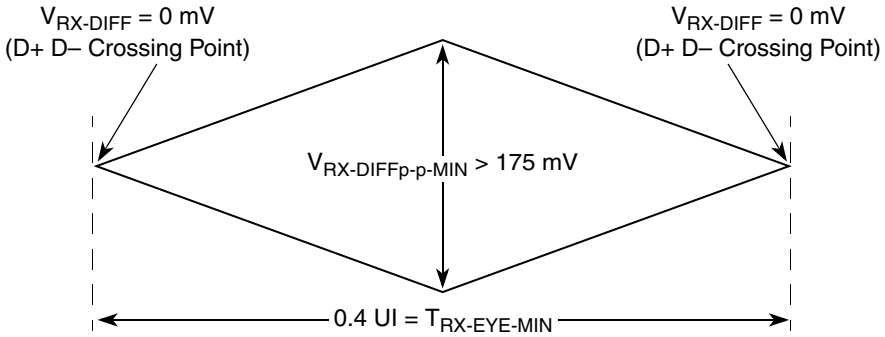


Figure 57. Minimum Receiver Eye Timing and Voltage Compliance Specification

17.5.1 Compliance Test and Measurement Load

The AC timing and voltage parameters must be verified at the measurement point, as specified within 0.2 inches of the package pins, into a test/measurement load shown in Figure 58.

NOTE

The allowance of the measurement point to be within 0.2 inches of the package pins is meant to acknowledge that package/board routing may benefit from D+ and D– not being exactly matched in length at the package pin boundary.

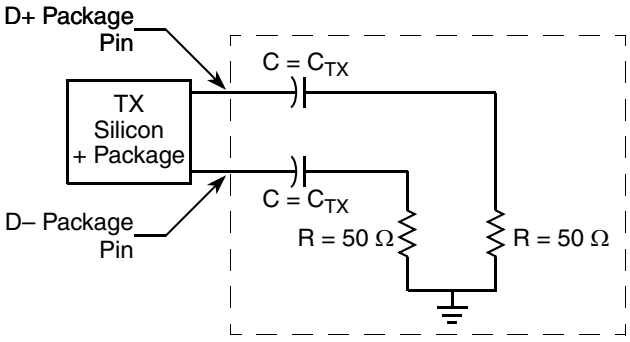


Figure 58. Compliance Test/Measurement Load

18 Package Description

This section details package parameters, pin assignments, and dimensions.

18.1 Package Parameters for the MPC8544E FC-PBGA

The package parameters for flip chip plastic ball grid array (FC-PBGA) are provided in Table 61.

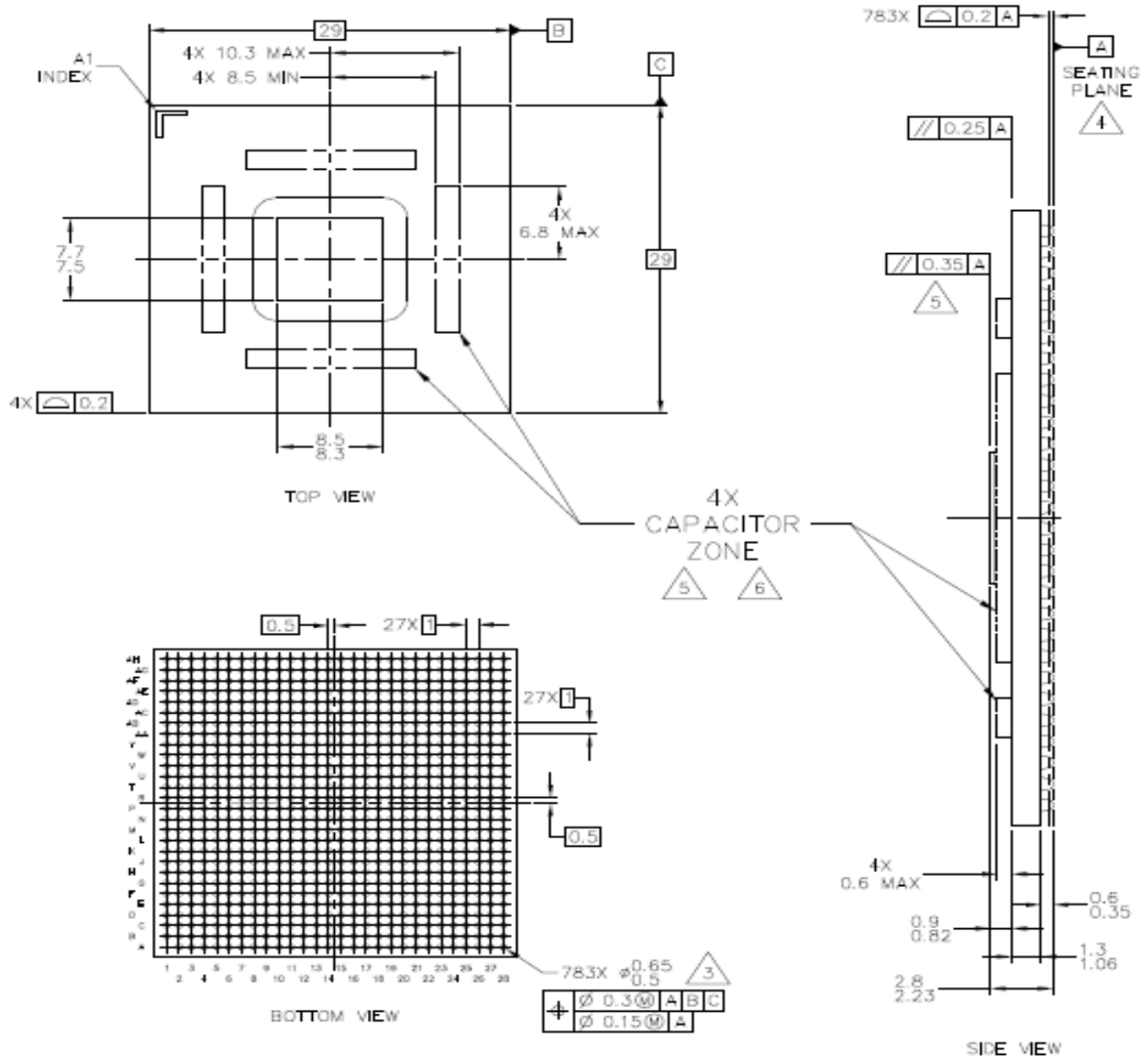
Table 61. Package Parameters

Parameter	PBGA[1]
Package outline	29 mm × 29 mm
Interconnects	783
Ball pitch	1 mm
Ball diameter (typical)	0.6 mm
Solder ball (Pb-free)	96.5% Sn 3.5% Ag

Note:
1. (FC-PBGA) without a lid.

18.2 Mechanical Dimensions of the MPC8544E FC-PBGA

Figure 59 shows the mechanical dimensions and bottom surface nomenclature of the MPC8544E, 783 FC-PBGA package without a lid.



Notes:
1. All dimensions are in millimeters.
2. Dimensions and tolerances per ASME Y14.5M-1994.
3. Maximum solder ball diameter measured parallel to datum A.
4. Datum A, the seating plane, is determined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.
6. Capacitors may not be present on all parts. Care must be taken not to short exposed metal capacitor pads.
7. All dimensions are symmetric across the package center lines, unless dimensioned otherwise.

Figure 59. Mechanical Dimensions and Bottom Surface Nomenclature of the MPC8544E FC-PBGA without a Lid

Table 62. MPC8544E Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
LCS6/DMA_DACK2	J16	O	BV_{DD}	1
LCS7/DMA_DDONE2	L18	O	BV_{DD}	1
LWE0/LBS0/LSDDQM[0]	J22	O	BV_{DD}	4, 8
LWE1/LBS1/LSDDQM[1]	H22	O	BV_{DD}	4, 8
LWE2/LBS2/LSDDQM[2]	H23	O	BV_{DD}	4, 8
LWE3/LBS3/LSDDQM[3]	H21	O	BV_{DD}	4, 8
LALE	J26	O	BV_{DD}	4, 7, 8
LBCTL	J25	O	BV_{DD}	4, 7, 8
LGPL0/LSDA10	J20	O	BV_{DD}	4, 8
LGPL1/LSDWE	K20	O	BV_{DD}	4, 8
LGPL2/LOE/LSDRAS	G20	O	BV_{DD}	4, 7, 8
LGPL3/LSDCAS	H18	O	BV_{DD}	4, 8
LGPL4/LGTA/LUPWAIT/ LPBSE	L20	I/O	BV_{DD}	28
LGPL5	K19	O	BV_{DD}	4, 8
LCKE	L17	O	BV_{DD}	—
LCLK[0:2]	H24, J24, H25	O	BV_{DD}	—
LSYNC_IN	D27	I	BV_{DD}	—
LSYNC_OUT	D28	O	BV_{DD}	—
DMA				
DMA_DACK[0:1]	Y13, Y12	O	OV_{DD}	4, 8, 9
DMA_DREQ[0:1]	AA10, AA11	I	OV_{DD}	—
DMA_DDONE[0:1]	AA7, Y11	O	OV_{DD}	—
Programmable Interrupt Controller				
UDE	AH15	I	OV_{DD}	—
MCP	AG18	I	OV_{DD}	—
IRQ[0:7]	AG22, AF17, AD21, AF19, AG17, AF16, AC23, AC22	I	OV_{DD}	—
IRQ[8]	AC19	I	OV_{DD}	—
IRQ[9]/DMA_DREQ3	AG20	I	OV_{DD}	1
IRQ[10]/DMA_DACK3	AE27	I/O	OV_{DD}	1
IRQ[11]/DMA_DDONE3	AE24	I/O	OV_{DD}	1
IRQ_OUT	AD14	O	OV_{DD}	2

Table 71 provides the thermal resistance with heat sink in open flow.

Table 71. Thermal Resistance with Heat Sink in Open Flow

Heat Sink with Thermal Grease	Air Flow	Thermal Resistance (°C/W)
Wakefield 53 × 53 × 25 mm pin fin	Natural convection	6.1
Wakefield 53 × 53 × 25 mm pin fin	1 m/s	3.0
Aavid 35 × 31 × 23 mm pin fin	Natural convection	8.1
Aavid 35 × 31 × 23 mm pin fin	1 m/s	4.3
Aavid 30 × 30 × 9.4 mm pin fin	Natural convection	11.6
Aavid 30 × 30 × 9.4 mm pin fin	1 m/s	6.7
Aavid 43 × 41 × 16.5 mm pin fin	Natural convection	8.3
Aavid 43 × 41 × 16.5 mm pin fin	1 m/s	4.3

Simulations with heat sinks were done with the package mounted on the 2s2p thermal test board. The thermal interface material was a typical thermal grease such as Dow Corning 340 or Wakefield 120 grease. For system thermal modeling, the MPC8544E thermal model without a lid is shown in Figure 60. The substrate is modeled as a block 29 × 29 × 1.18 mm with an in-plane conductivity of 18.0 W/m•K and a through-plane conductivity of 1.0 W/m•K. The solder balls and air are modeled as a single block 29 × 29 × 0.58 mm with an in-plane conductivity of 0.034 W/m•K and a through plane conductivity of 12.1 W/m•K. The die is modeled as 7.6 × 8.4 mm with a thickness of 0.75 mm. The bump/underfill layer is modeled as a collapsed thermal resistance between the die and substrate assuming a conductivity of 6.5 W/m•K in the thickness dimension of 0.07 mm. The die is centered on the substrate. The thermal model uses approximate dimensions to reduce grid. Please refer to Figure 59 for actual dimensions.

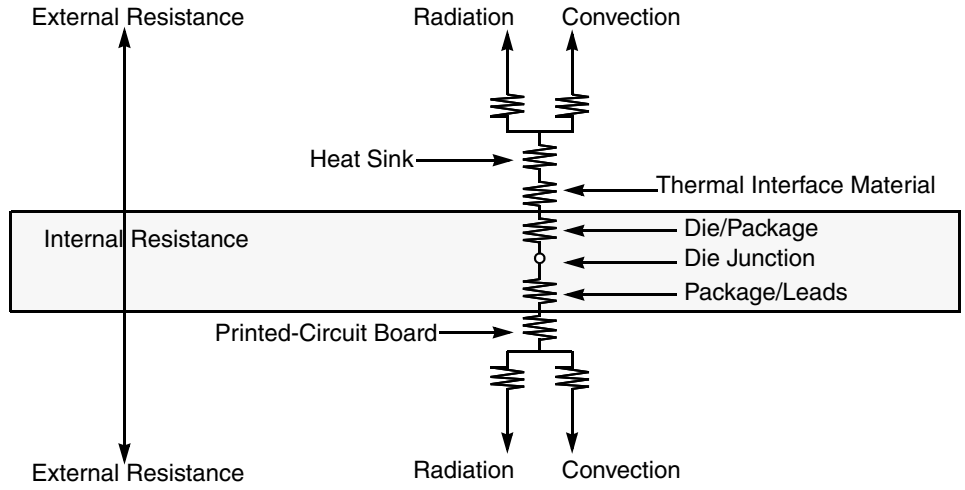
20.2 Recommended Thermal Model

Table 72 shows the MPC8544E thermal model.

Table 72. MPC8544EThermal Model

Conductivity	Value	Units
Die (7.6 × 8.4 × 0.75mm)		
Silicon	Temperature dependent	—
Bump/Underfill (7.6 × 8.4 × 0.070 mm) Collapsed Thermal Resistance		
Kz	6.5	W/m•K
Substrate (29 × 29 × 1.18 mm)		
Kx	18	W/m•K
Ky	18	
Kz	1.0	

Figure 62 depicts the primary heat transfer path for a package with an attached heat sink mounted to a printed-circuit board.



(Note the internal versus external package resistance.)

Figure 62. Package with Heat Sink Mounted to a Printed-Circuit Board

The heat sink removes most of the heat from the device. Heat generated on the active side of the chip is conducted through the silicon and through the heat sink attach material (or thermal interface material), and finally to the heat sink. The junction-to-case thermal resistance is low enough that the heat sink attach material and heat sink thermal resistance are the dominant terms.

20.3.2 Thermal Interface Materials

A thermal interface material is required at the package-to-heat sink interface to minimize the thermal contact resistance. For those applications where the heat sink is attached by spring clip mechanism, Figure 63 shows the thermal performance of three thin-sheet thermal-interface materials (silicone, graphite/oil, floroether oil), a bare joint, and a joint with thermal grease as a function of contact pressure. As shown, the performance of these thermal interface materials improves with increasing contact pressure. The use of thermal grease significantly reduces the interface thermal resistance. The bare joint results in a thermal resistance approximately six times greater than the thermal grease joint.

21.5 Connection Recommendations

To ensure reliable operation, it is highly recommended to connect unused inputs to an appropriate signal level. All unused active low inputs should be tied to V_{DD}, TV_{DD}, BV_{DD}, OV_{DD}, GV_{DD}, and LV_{DD} as required. All unused active high inputs should be connected to GND. All NC (no connect) signals must remain unconnected. Power and ground connections must be made to all external V_{DD}, TV_{DD}, BV_{DD}, OV_{DD}, GV_{DD}, and LV_{DD}, and GND pins of the device.

21.6 Pull-Up and Pull-Down Resistor Requirements

The MPC8544E requires weak pull-up resistors (2–10 kΩ is recommended) on open drain type pins including I^2C pins and MPIC interrupt pins.

Correct operation of the JTAG interface requires configuration of a group of system control pins as demonstrated in Figure 69. Care must be taken to ensure that these pins are maintained at a valid deasserted state under normal operating conditions as most have asynchronous behavior and spurious assertion will give unpredictable results.

The following pins must NOT be pulled down during power-on reset: TSEC3_TXD[3], $\overline{\text{HRESET\_REQ}}$, TRIG_OUT/READY/$\overline{\text{QUIESCE}}$, MSRCID[2:4], ASLEEP. The $\overline{\text{DMA\_DACK}}$[0:1] and $\overline{\text{TEST\_SEL}}$ pins must be set to a proper state during POR configuration. Refer to the pinout listing table (Table 62) for more details. Refer to the *PCI 2.2 Local Bus Specifications,* for all pullups required for PCI.

21.7 Output Buffer DC Impedance

The MPC8544E drivers are characterized over process, voltage, and temperature. For all buses, the driver is a push-pull single-ended driver type (open drain for I^2C). To measure Z_0 for the single-ended drivers, an external resistor is connected from the chip pad to OV_{DD} or GND. Then, the value of each resistor is varied until the pad voltage is $OV_{DD}/2$ (see Figure 67). The output impedance is the average of two components, the resistances of the pull-up and pull-down devices. When data is held high, SW1 is closed (SW2 is open) and R_P is trimmed until the voltage at the pad equals $OV_{DD}/2$. R_P then becomes the

23 Document Revision History

This table provides a revision history for the MPC8544E hardware specification.

Table 76. MPC8544E Document Revision History

Revision	Date	Substantive Change(s)
8	09/2015	• In Table 10 and Table 12, removed the output leakage current rows and removed table note 4.
7	06/2014	• In Table 75, “Device Nomenclature,” added full Pb-free part code. • In Table 75, “Device Nomenclature,” added footnotes 3 and 4.
6	05/2011	• Updated the value of t_{JTKLDX} to 2.5 ns from 4ns in Table 50.
5	01/2011	• Updated Table 75.
4	09/2010	• Modified local bus information in Section 1.1, “Key Features,” to show max local bus frequency as 133 MHz. • Added footnote 28 to Table 62. • Updated solder-ball parameter in Table 61.
3	11/2009	• Update Section 20.3.4, “Temperature Diode,” • Update Table 61 Package Parameters from 95.5%sn to 96.5%sn
2	01/2009	• Update power number table to include 1067 MHz/533 MHz power numbers. • Remove Part number tables from Hardware spec. The part numbers are available on Freescale web site product page. • Removed I/O power numbers from the Hardware spec. and added the table to bring-up guide application note. • Update t_{DDKHMP}, t_{DDKHME} in Table 18. • Updated RX_CLK duty cycle min, and max value to meet the industry standard GMII duty cycle. • Update paragraph Section 21.3, “Decoupling Recommendations.” • Update Figure 5 DDR Output Timing Diagram. • In Table 40, removed note 1 and renumbered remaining note. • Update Section 22, “Device Nomenclature,” with regards to Commercial Tier.
1	06/2008	Update in Table 18 DDR SDRAM Output AC Timing Specifications tMCK Max value Improvement to Section 16, “High-Speed Serial Interfaces (HSSI) Update Figure 59 Mechanical Dimensions Update in Table 48 Local Bus General Timing Parameters—PLL Bypassed
0	04/2008	Initial release.

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